## Features

- 650V,7A
  R<sub>DS (ON)</sub> <600m Ω @V<sub>GS</sub>=10V TYP:523m Ω
- Advanced Super junction technology
- Extremely Low ON Resistance

# Applications

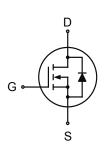
- Power faction correction (PFC)
- Switched mode power supplies (SMPS)
- Uninterruptible power supply (UPS)
- LED lighting powe



Device Marking	Device	Device Package	Reel Size	Tape width	Quantity (PCS)		
C65R600KM	APC65R600KM	TO-252	-	-	2500		

## ABSOLUTE MAXIMUM RATINGS (TJ=25℃ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	650	V
Gate-Source Voltage	V <sub>GS</sub>	±30	V
Continuous Drain Current (T <sub>c</sub> =25°C)	Ι <sub>D</sub>	7	A
Continuous Drain Current (T <sub>c</sub> =100°C)	Ι <sub>D</sub>	4.4	A
Pulsed Drain Current <sup>(1)</sup>	I <sub>DM</sub>	28	A
Single Pulsed Avalanche Energy (2)	E <sub>AS</sub>	190	mJ
Drain Power Dissipation	PD	30	W
Thermal Resistance from Junction to Case	R <sub>ejc</sub>	4.17	°C/W
Thermal Resistance- Junction to Ambient	R <sub>0JA</sub>	62.5	°C/W
Junction Temperature	TJ	150	°C
Storage Temperature	T <sub>STG</sub>	-55~ +150	°C
Maximum Lead temperature for soldering Purpose	TL	300	°C



**Schematic Diagram** 

TO-252



## MOSFET ELECTRICAL CHARACTERISTICS(TJ=25℃ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Туре	Мах	Unit
Static Characteristics		·				
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> =250µA	650	-	-	V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> =650V, V <sub>GS</sub> = 0V	-	-	100	nA
Gate-body leakage current	I <sub>GSS</sub>	$V_{GS}$ = ± 30V, $V_{DS}$ = 0V	-	-	±100	nA
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250µA	2.0	3.3	4.0	V
Forward Transconductance (3)	<b>g</b> fs	V <sub>DS</sub> =25V, I <sub>D</sub> =7A	-	4.9	-	S
Drain-source on-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =3.5A	-	523	600	mΩ
Dynamic characteristics						
Input Capacitance	C <sub>iss</sub>		-	423	-	
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V, f =1.0MHz	-	26	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	1.7	-	
Switching characteristics <sup>(3,4)</sup>						
Turn-on delay time	t <sub>d(on)</sub>		-	11.2	-	
Turn-on rise time	tr	V <sub>DD</sub> =325V, I <sub>D</sub> =7A, R <sub>G</sub> =24Ω,	-	28.6	-	ns
Turn-off delay time	$t_{d(off)}$	V <sub>G</sub> =10V	-	46.7	-	
Turn-off fall time	t <sub>f</sub>	-	-	24.4	-	
Total Gate Charge	Qg		-	16.4	-	
Gate-Source Charge	Qgs	$V_{DS}$ =520V, I <sub>D</sub> =7A,	-	3.5	-	nC
Gate-Drain Charge	Qgd	V <sub>GS</sub> =10V	-	8.3	-	
Source-Drain Diode characteristics						
Diode Forward voltage	V <sub>SD</sub>	T <sub>c</sub> =25℃, V <sub>GS</sub> =0V, I <sub>S</sub> =7A	-	0.87	1.4	V
Diode Forward current	I <sub>S</sub>	T <sub>c</sub> =25℃	-	-	7	Α
Body Diode Reverse Recovery Time <sup>(3)</sup>	trr	T <sub>c</sub> =25℃, IF=7A,di/dt=100A/us		340		ns
Body Diode Reverse Recovery Charge	Qrr	T <sub>c</sub> =25℃, IF=7A,di/dt=100A/us		2.5		uc

#### Notes:

- 1. Pluse width limited by maximum junction temperature
- 2. L=79mH, IAS=2.2A, VDD=100V, VG=10V, RG=25 $\Omega$ , starting TJ=25°C
- 3. Pulse Test: Pulse width  $\leq$ 300µs, Duty cycle $\leq$ 2%
- 4. Essentially independent of operating temperature

#### **Typical Performance Characteristics**

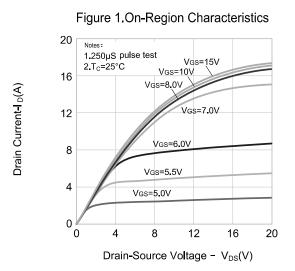


Figure 3.On-Resistance Variation vs. Drain-Current,Gate Voltage

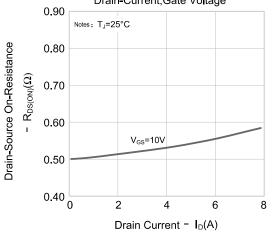
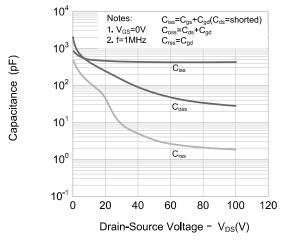


Figure 5.Capacitance Characteristics



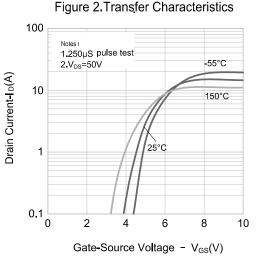


Figure 4.Body Diode Forward Voltage Variation vs.Source Current and Temperature

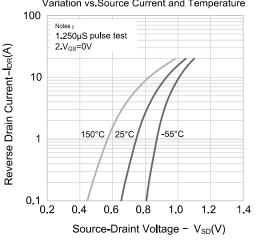
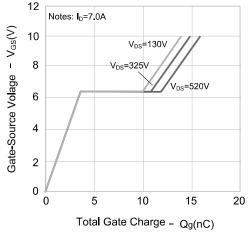


Figure 6.Gate Charage Characteristics



AII POWER DATA SHEET



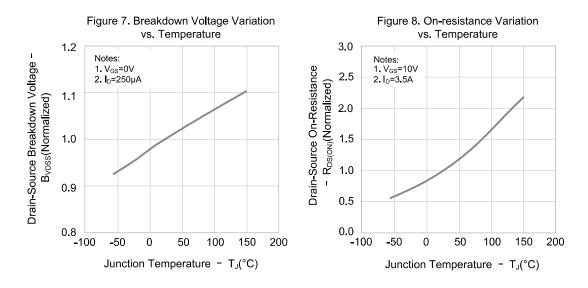
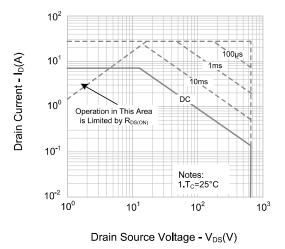
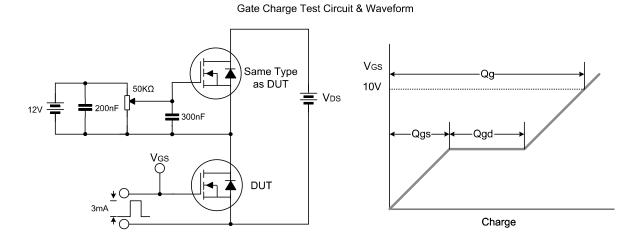


Figure 9 Max. Safe Operating Area

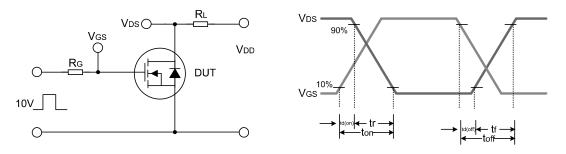




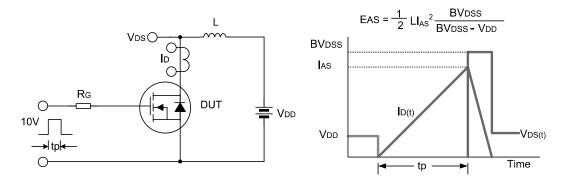
### **Test Circuit**



Resistive Switching Test Circuit & Waveform

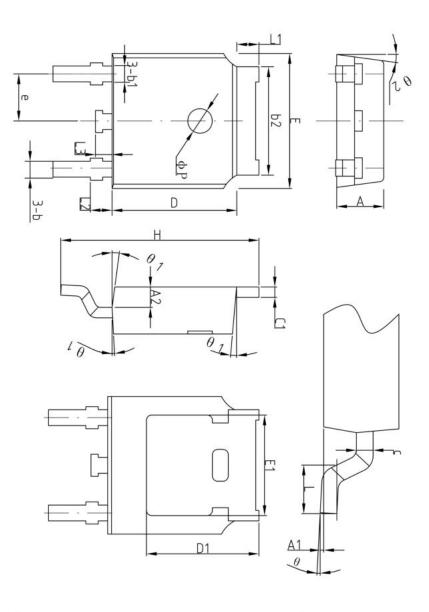


#### Unclamped Inductive Switching Test Circuit & Waveform





## Package Dimensions of TO-252



02	01	θ	φP	L3	12	5		н	e	E1	m	D1	D	c1	C	b2	ь1	σ	A2	A1	A	SYMBOL
ů	Ω	0.				0.90	1.40	9.70		ı	6.50	I	6.0	0.47	0.47	5.13		0.71	0.90	0	2.2	MIN
7.	7.	Î	1.2	0.8	1.05	I	1.50	10.10	2.286BSC	4.80	6.60	5.30	6.10	0.50	0.50	5.33	0.76	0.76	1.01	1	2.30	NON
œ.	9.	œ				1.25	1.70	10.40	0	I	6.70	1	6.20	0.60	0.60	5.46		0.86	1.10	0.10	2.38	MAX

All Power Microelectronics Co.,Ltd

## **Revision History**

Revision	Release	Remark				
V1.0	2023/11/16	Initial Release				

#### Disclaimer

The information given in this document describes the independent performance of the product,but similar performance is not guaranteed under other working conditions,and cannot be guaranteed when installed with other products or equipment. To achieve the required performance of the product in actual scenarios, the customer should conduct a complete application test to assess the functionality of the product.

Allpower assumes no responsibility for equipment failures result from using products at values that exceed the ratings, operating conditions, or other parameters listed in the product specifications.

The product described in this specification is not applicable for aerospace or other applications which requires high reliability.Customers using or selling these products for use in medical,life-saving,or life-sustaining applications do so at their own risk and agree to fully indemnify.

Due to product or technical improvements, the information described or contained herein may be changed without prior notice.